

## IN THE CLAIMS

Please amend claims 1, 4-5, 9-13 and cancel claims 2-3 and 14-28 as follows:

1. (Currently Amended) A method for fabricating a capacitor formed on a substrate wherein said capacitor is utilized in a semiconductor device, said method comprising the steps of:

designating a salicide gate for use with said semiconductor device;

configuring a self-aligned contact for use with said semiconductor device;

and

patterning a poly gate on said substrate with a hard mask;

performing a cell implant thereof;

depositing TEOS, SiN, BPTEOS on said substrate;

performing an IPO-1 planarization upon a layer formed on said substrate;

and

combining said salicide gate and a self-aligned contact in a memory cell area of said semiconductor device to thereby permit the efficient shrinkage of memory cell size without an additional mask or weakening of associated circuit performance.

2. - 3. (cancelled)

4. (Currently Amended) ~~The method of claim 3 further comprising the step of:~~ A method for fabricating a capacitor formed on a substrate wherein said capacitor is utilized in a semiconductor device, said method comprising the steps of:

designating a salicide gate for use with said semiconductor device;

configuring a self-aligned contact for use with said semiconductor device;

patterning a poly gate on said substrate with a hard mask;

performing a cell implant thereof;

depositing TEOS, SiN, BPTEOS on said substrate;  
performing an IPO-1 planarization upon a layer formed on said substrate;  
combining said salicide gate and a self-aligned contact in a memory cell area  
of said semiconductor device to thereby permit the efficient shrinkage of memory  
cell size without an additional mask or weakening of associated circuit  
performance; and

performing an anisotropic etch back thereof to stop on said poly gate  
utilizing high selectivity between said poly gate and said anisotropic etch back,  
wherein said anisotropic etch back comprises anisotropic etch back based on a  
combination of oxide and SiN.

5. (Currently Amended) ~~The method of claim 4 further comprising the steps of:~~ A  
method for fabricating a capacitor formed on a substrate wherein said capacitor is  
utilized in a semiconductor device, said method comprising the steps of:

designating a salicide gate for use with said semiconductor device;  
configuring a self-aligned contact for use with said semiconductor device;  
patterning a poly gate on said substrate with a hard mask;  
performing a cell implant thereof;  
depositing TEOS, SiN, BPTEOS on said substrate;  
performing an IPO-1 planarization upon a layer formed on said substrate; a  
combining said salicide gate and a self-aligned contact in a memory cell area  
of said semiconductor device to thereby permit the efficient shrinkage of memory  
cell size without an additional mask or weakening of associated circuit  
performance;

defining a logic poly gate;  
performing an LDD implant upon said substrate; and  
forming a spacer deposition layer upon said substrate.

6. (Original) The method of claim 5 further comprising the steps of:  
performing a spacer TEOS dry etch followed by a stop at SiN;  
utilizing an additional photo mask to open an associated DRAM array; and  
utilizing a wet dip upon said substrate and said layers thereof to remove a spacer TEOS.
7. (Original) The method of claim 6 further comprising the steps of:  
performing a spacer SiN dry etch upon said substrate and said layers thereof followed by a stop on a TEOS; and  
utilizing a wet dip upon said substrate and said layers thereof to remove said spacer TEOS.
8. (Original) The method of claim 7 further comprising the step of:  
forming a Co-salicide upon said substrate for use with said semiconductor device.
9. (Currently Amended) ~~The method of claim 8 further comprising the step of:~~ A method for fabricating a capacitor formed on a substrate wherein said capacitor is utilized in a semiconductor device, said method comprising the steps of:  
designating a salicide gate for use with said semiconductor device;  
configuring a self-aligned contact for use with said semiconductor device;  
patterning a poly gate on said substrate with a hard mask;  
performing a cell implant thereof;  
depositing TEOS, SiN, BPTEOS on said substrate;  
performing an IPO-1 planarization upon a layer formed on said substrate; a  
combining said salicide gate and a self-aligned contact in a memory cell area of said semiconductor device to thereby permit the efficient shrinkage of memory cell size without an additional mask or weakening of associated circuit performance;

performing an anisotropic etch back thereof to stop on said poly gate  
utilizing high selectivity between said poly gate and said anisotropic etch back,  
wherein said anisotropic etch back comprises anisotropic etch back based on a  
combination of oxide and SiN;

defining a logic poly gate;

performing an LDD implant upon said substrate;

forming a spacer deposition layer upon said substrate;

performing a spacer TEOS dry etch followed by a stop at SiN;

utilizing an additional photo mask to open an associated DRAM array;

utilizing a wet dip upon said substrate and said layers thereof to remove a  
spacer TEOS;

performing a spacer SiN dry etch upon said substrate and said layers thereof  
followed by a stop on a TEOS;

utilizing a wet dip upon said substrate and said layers thereof to remove said  
spacer TEOS;

forming a Co-salicide upon said substrate for use with said semiconductor  
device; and

utilizing said capacitor formed between a metal-one layer and a metal-two  
layer upon said substrate in said semiconductor device, wherein said capacitor  
comprises an MIM capacitor.

10. (Currently Amended) The method of claim 9 1 wherein said semiconductor  
device comprises a DRAM-based semiconductor device.

11. (Currently Amended) The method of claim 9 2 wherein said poly gate  
comprises a DRAM poly gate.

12. (Currently Amended) The method of claim 9 2 wherein said cell implant  
comprises a cell LDD implant.

13. (Currently Amended) The method of claim 9 ± wherein said capacitor comprises an MIM capacitor.

14. - 29. (Cancelled)